

**AMENDMENT TO THE DRAWING(S)**

Please find enclosed a replacement sheet for the drawing sheet on which Fig. 1 appears with a proposed amendment to Fig. 1 for the approval of the Examiner.

### **REMARKS/ARGUMENTS**

The applicants' attorneys appreciate the Examiner's thorough search and remarks.

An enclosed proposed amendment to Fig. 1 amends the leader line leading from reference numeral 10 on the right-hand side of Fig. 1 so that the leader line properly points to power MOSFET 10 instead of to conductive pad 16.

Claims 1-5 were rejected under 35 U.S.C. §102(e) as being anticipated by Shinohara, US 2002/0109211. Reconsideration of the rejection is respectfully requested.

Claim 1 has been amended to call for:

a second lead frame having a second conductive pad, a second power device disposed on and electrically connected to said second conductive pad, and a second heatsink in thermal contact with said second conductive pad, wherein there is no intermediate body between said second conductive pad and said second heatsink that retards heat transference from said second power device to said second heatsink, and wherein said second heatsink is larger than said first heatsink whereby a thermal gradient between said heatsinks may be reduced to reduce thermal stresses on said module.

As set forth in the specification at page 7, paragraph [0025], by enlarging one heatsink, thermal stresses may be minimized. Shinohara, however, fails to show or suggest such a feature.

Furthermore, claim 1 calls for "no intermediate body" between the first conductive pad and the first heatsink, and the second conductive pad and the second heatsink.

On the other hand, Shinohara shows an intermediate body 10 disposed between the heatsink and the conductive pad. Intermediate body 10 is a resin. Paragraph [0052]. While Shinohara claims that intermediate body 10 is better than the prior art in heat transfer, it must be recognized that a resin inherently retards the transfer of heat.

For at least the foregoing reasons Shinohara does not anticipate claim 1. Reconsideration is requested.

Each of claims 2 and 4-11 depends from claim 1, and, therefore, includes at least the limitation thereof. Each of these claims includes additional limitations which in combination

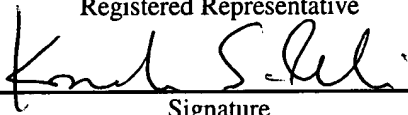
with those of claim 1 are not shown or suggested by the art of record. Reconsideration is requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on November 9, 2005:

Kourosh Salehi

Name of applicant, assignee or  
Registered Representative

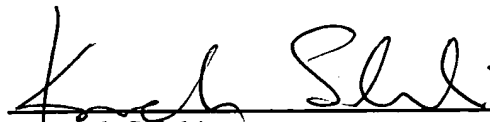


Signature

November 9, 2005

Date of Signature

Respectfully submitted,



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